



# The Silicon TPC System

EUDET Extended SC meeting

27 August 2007

Jan Timmermans

NIKHEF

# JRA2 activity/task

- Silicon TPC readout (“SiTPC”)
  - development MediPix → TimePix chip
  - development diagnostic endplate module  
incl. DAQ

Purpose: a SiTPC based monitoring system

Partners:

ALU Freiburg, Bonn, CEA Saclay, CERN, NIKHEF

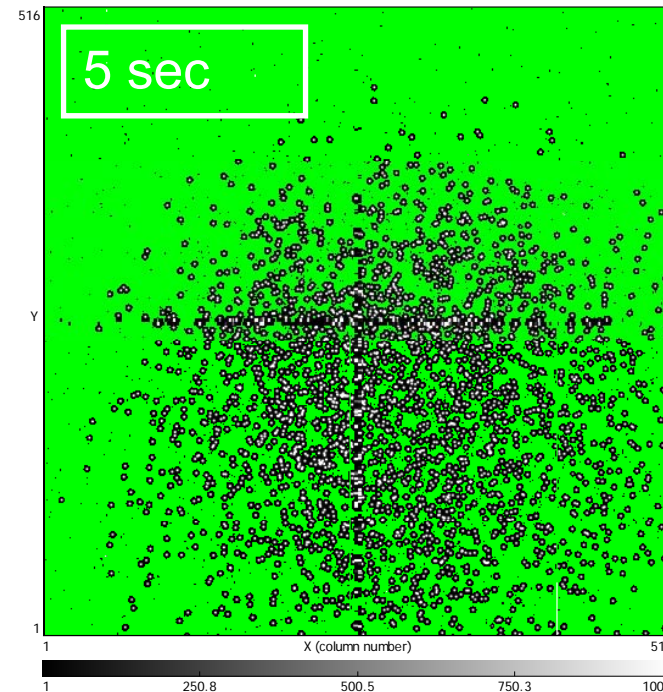
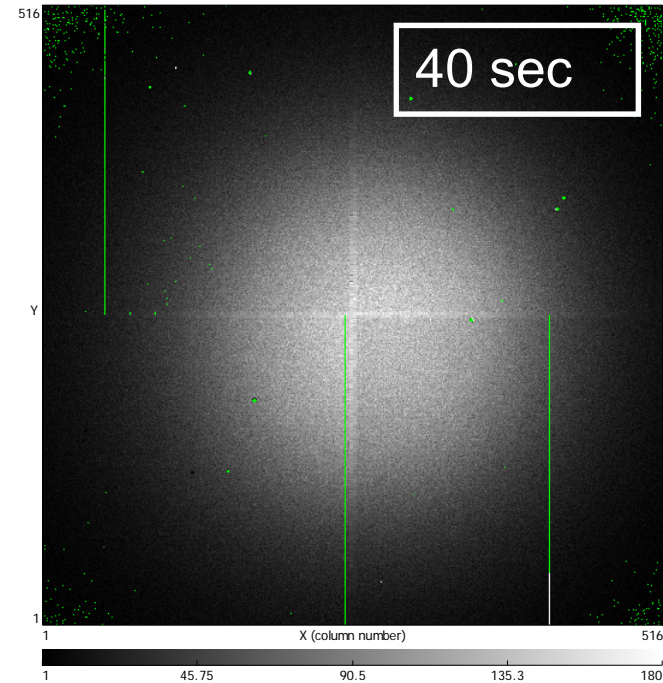
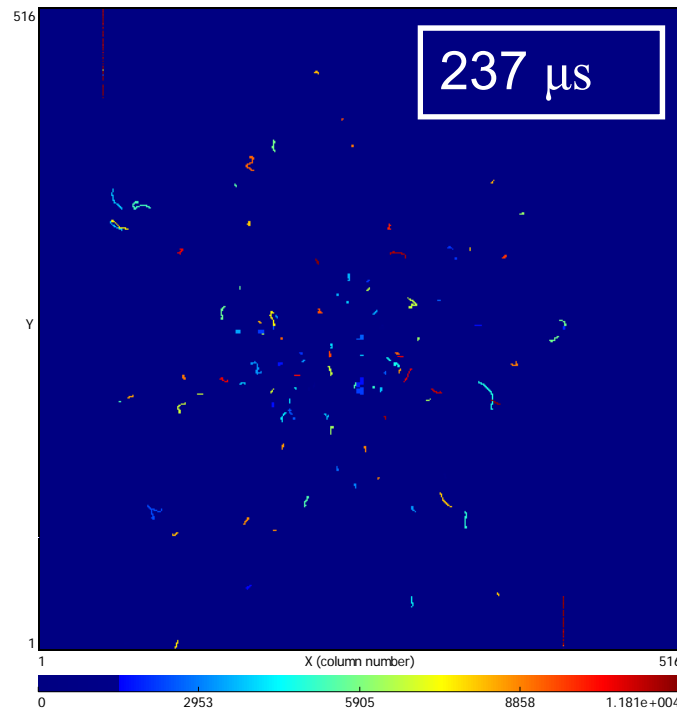
Associate: Bucarest

## SITPC Tasks:

- ✓ Develop the Timepix chip that allows to measure the 3<sup>rd</sup> coordinate (drift time)
- ✓ Implementation of Timepix together with GEM and Micromegas into diagnostic endplate system (in progress)
- Performance measurements in test infrastructure at DESY
- Develop simulation framework
- Develop DAQ system and integrate in overall DAQ of EUDET infrastructure

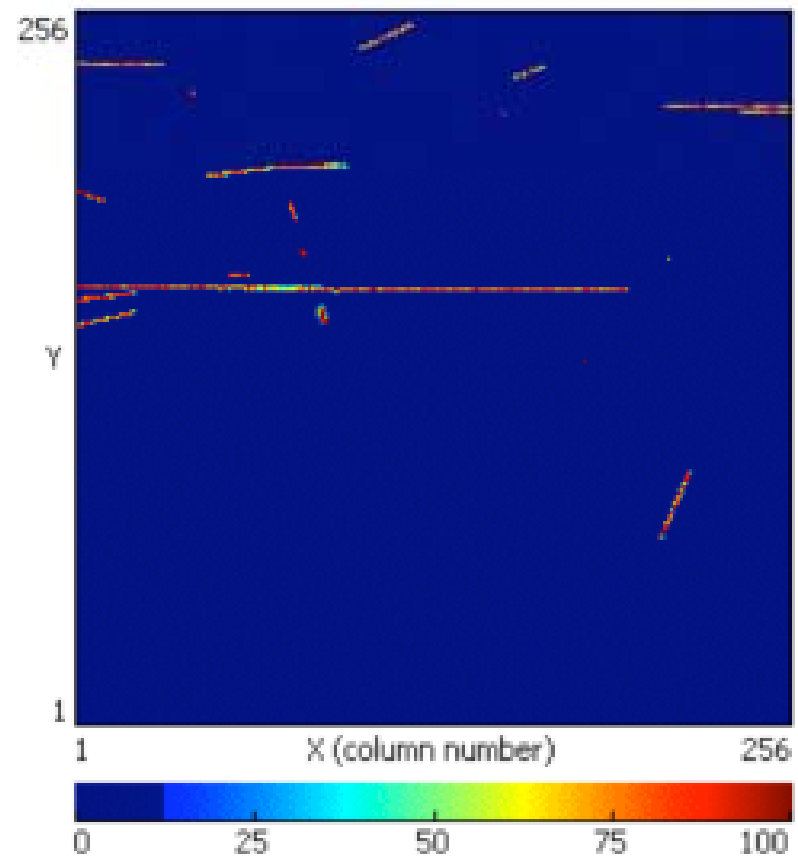
CERN (Xavi Llopart/Michael Campbell):  
first Timepix quad (+ 300  $\mu\text{m}$  Si sensor)

- Top-right: Medipix counting mode ( $^{55}\text{Fe}$ )
- Bottom-left: Time mode ( $^{90}\text{Sr}$ )
- Bottom-right: time-over-threshold ( $^{241}\text{Am}$ )



Erik Heijne: Timepix (single chip + Si sensor) parallel to beam

## H6 120 GeV/c PION BEAM



**ANALOG MODE TOT**  
TYPICAL SIGNAL ~80 counts



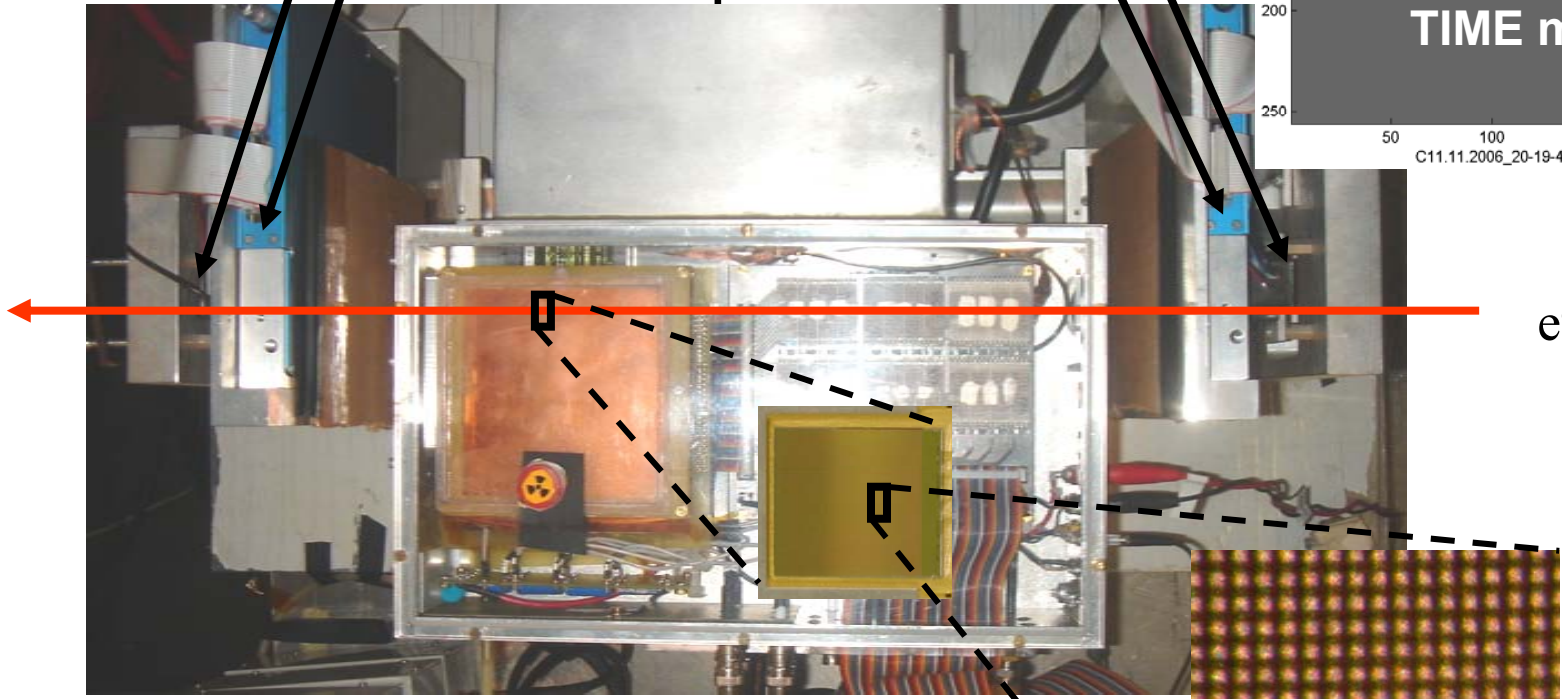
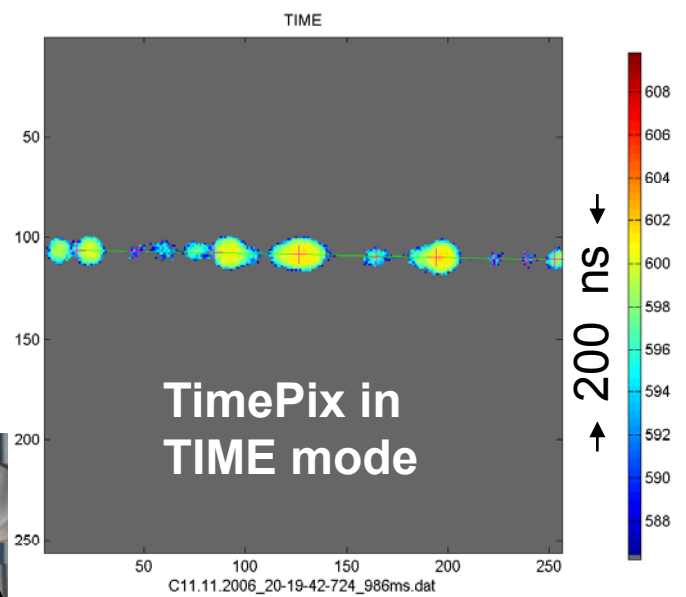
# Test beam setup and event

Freiburg

trigger counters ~ 1cm wide

Si telescope (y position ~20 μm precision)

- Test/beam setup



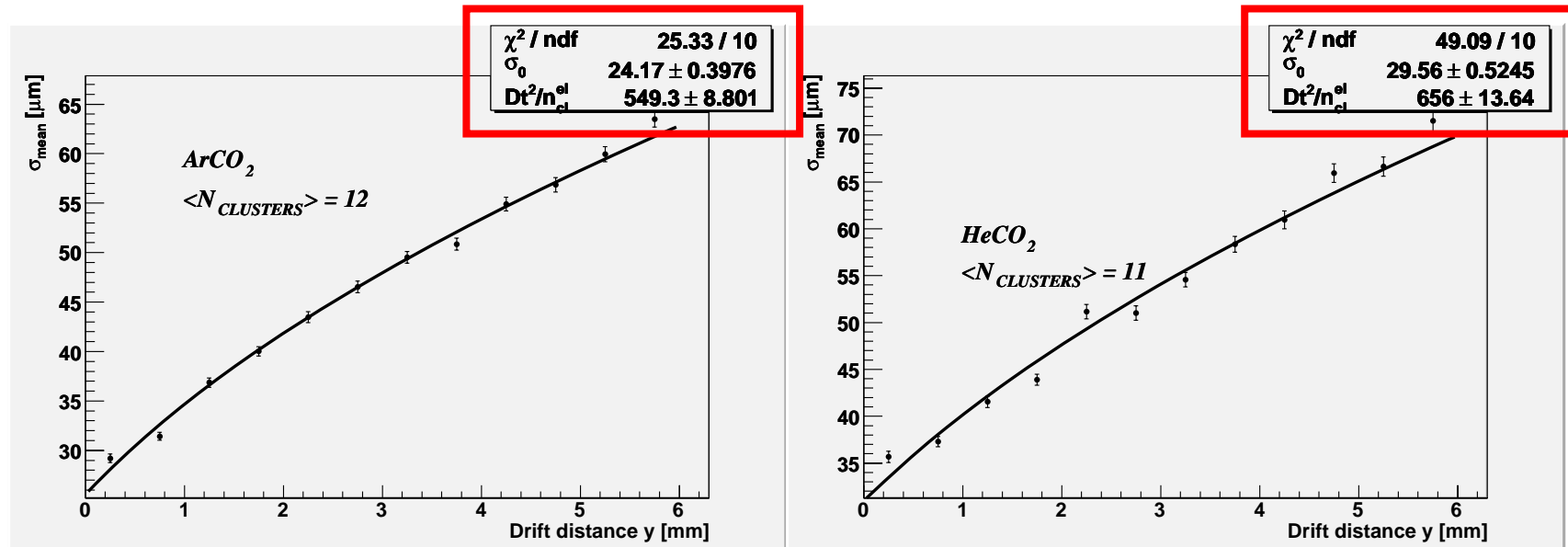
e<sup>-</sup> from DESY II

Triple GEM stack  
of 10x10 cm<sup>2</sup>

TimePix chip  
14x14 mm<sup>2</sup>

pitch of  
pixels  
55 μm

# Highlight of TimePix results



High statistics runs with standard GEM (140  $\mu\text{m}$  pitch).

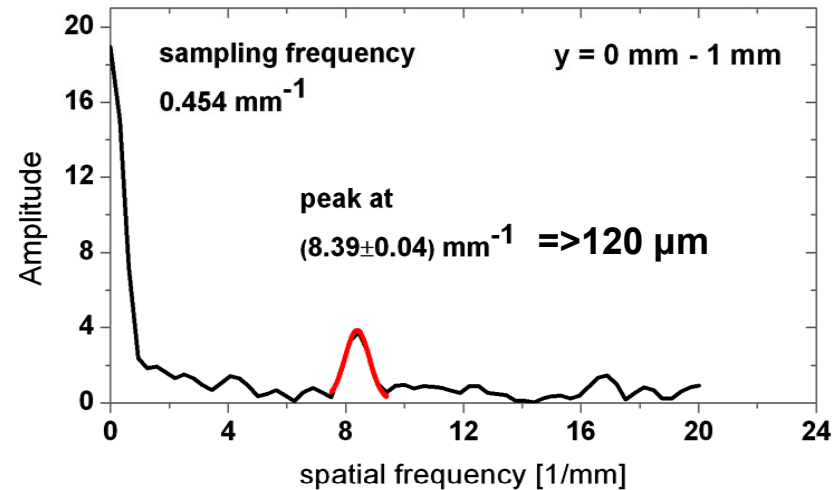
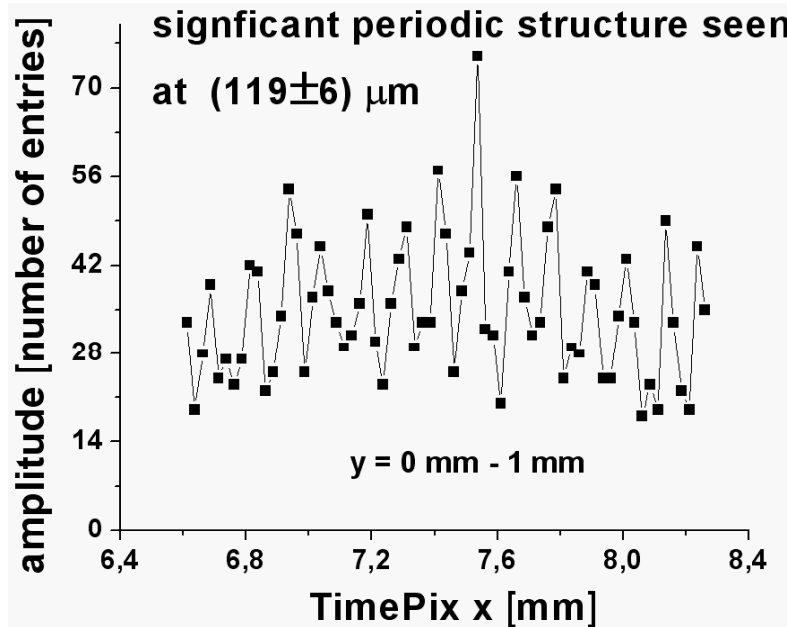
Mixed Mode setting of the TimePix: Every other pixel measures charge, the TIME is recorded for the other half of the pixels.

The following observations are made:

- Different cluster separation algorithm are employed: the change for  $\sigma_0$  is a few  $\mu\text{m}$ .
- The time information is corrected for the walk (dependence of the time of arrival measured on the amount charge deposited).
- A resolution in  $y$  of  $<16$  ns/cluster is achieved (about 0.45 mm). The clock runs with 48 MHz.
- Additional cut on the time results in an improvement for  $\sigma_0$  of about  $1\mu\text{m}$ .
- A change of the slope parameter  $D_t^2/n_{eff}$  is observed as the cluster size increases due to merged primary clusters (increase of the effective number of electrons).

# Substructure due to GEM hole pitch

standard GEM



Is the resolution of a cluster yet affected by the finite pitch of the holes?

Test runs are taken recently with different orientation with respect to the track and with smaller pitched GEMs ( $80\mu\text{m}$ ).

Results are expected to be available soon.



## SiTPC activities in BN

### Status:

Work towards construction of a GEM-Timepix-Module for JRA2 Large Prototype

- test setup (Muros+Pixelman) running in Bonn
- single chip carrier for gluing into endplate produced and tested
- small prototype construction ongoing
- started design work for LP module (EUDET deliverable)

### Plans:

- small prototype available in fall, then tests in lab + testbeam
- produce an initial 3-GEM module with ( $n > 1$ ) Timepix chips compatible with LP by end of year (to meet milestone)
- integration with JRA1 Trigger/DAQ system

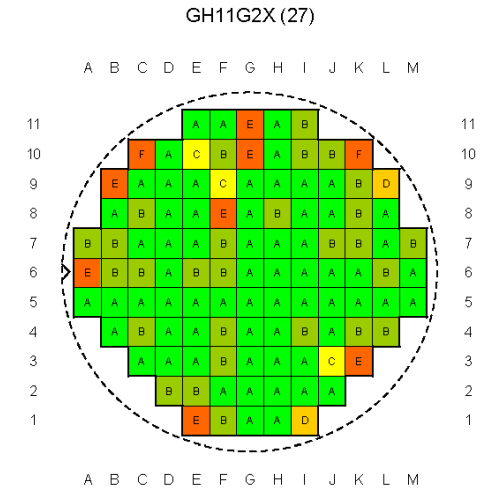
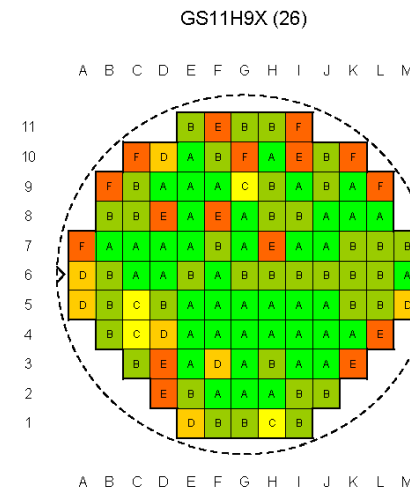
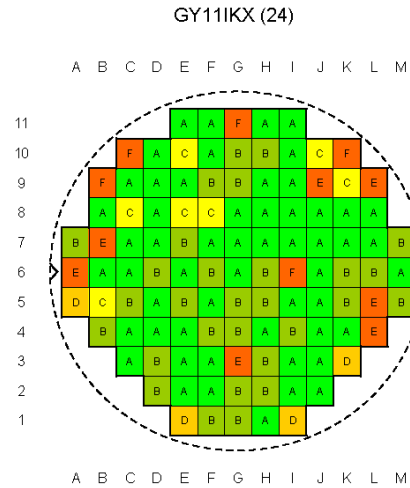
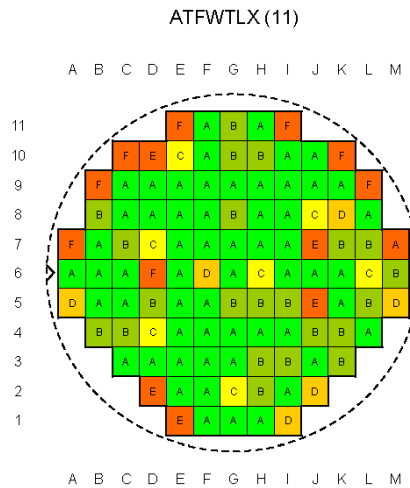
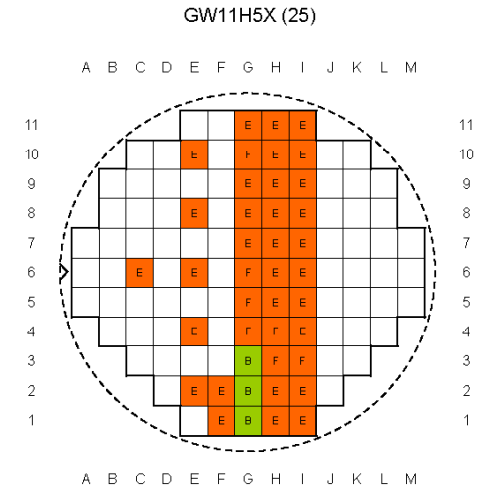
### Financial:

Postdoc (M.Killenberg) 50% on JRA2/SiTPC, 50% on NA2/ANALYS  
Cashflow as planned



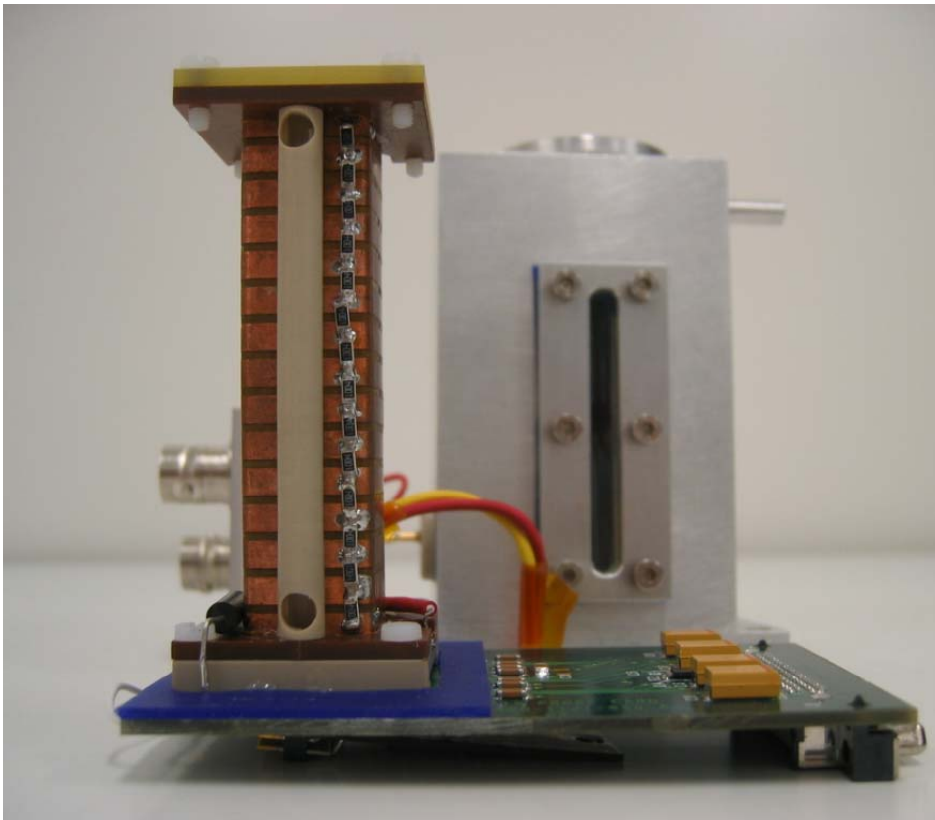
# TimePix wafer tests

Wafers		Classes						Total
N°	ID	A	B	C	D	E	F	
11	ATFWTLX	59	22	7	6	5	8	107
24	GY11IKX	55	29	7	4	7	5	107
25	GW11H5X	-	3	-	-	31	7	41
26	GS11H9X	43	37	4	7	9	7	107
27	GH11G2X	65	28	3	2	7	2	107
<b>Totals</b>		222	116	21	19	28	22	428
<b>Percentages (%)</b>		51.9	27.1	4.9	4.4	6.6	5.1	100

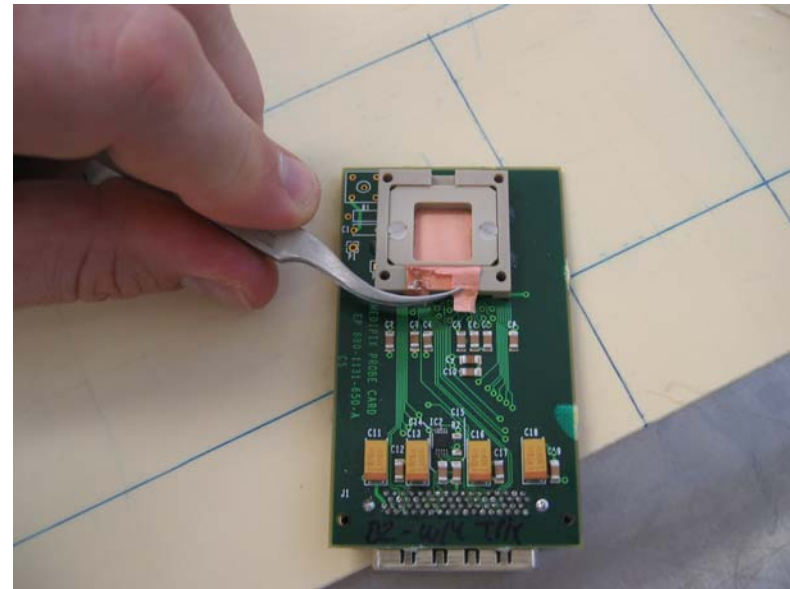
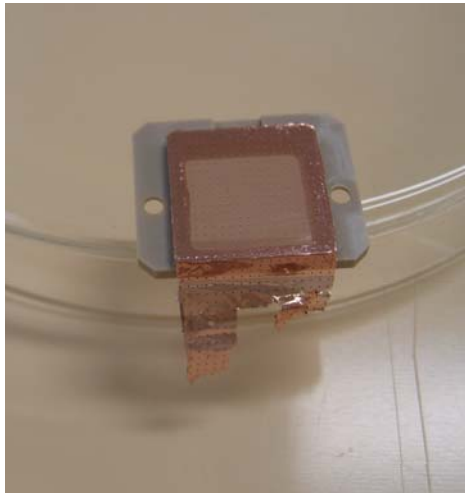


8 more wafers will be probed in mid-September

- Box mounted on TimePix board:

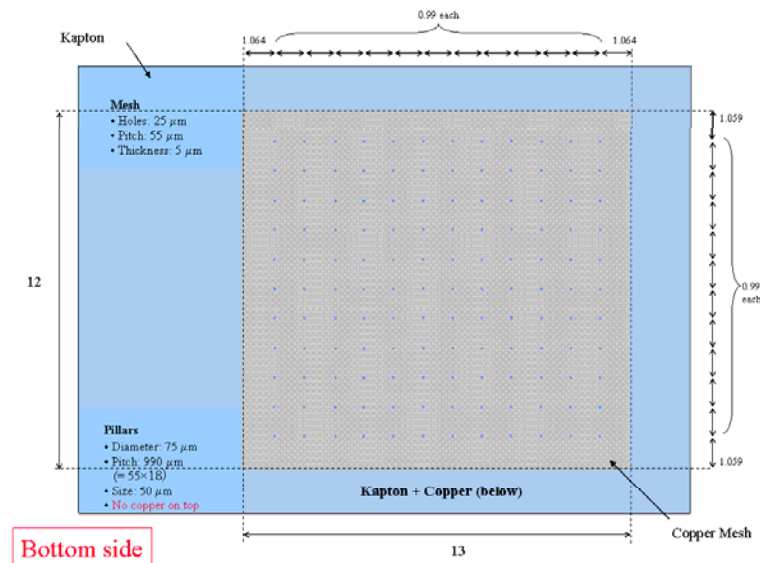


- Mesh made at Saclay of 12x12 mm<sup>2</sup> size



- Specific Micromegas meshes build at CERN should be available soon

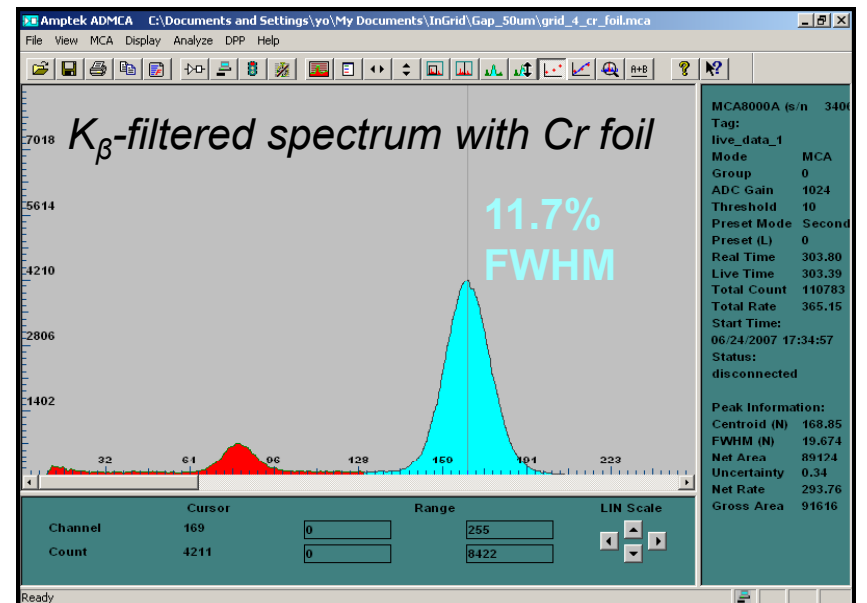
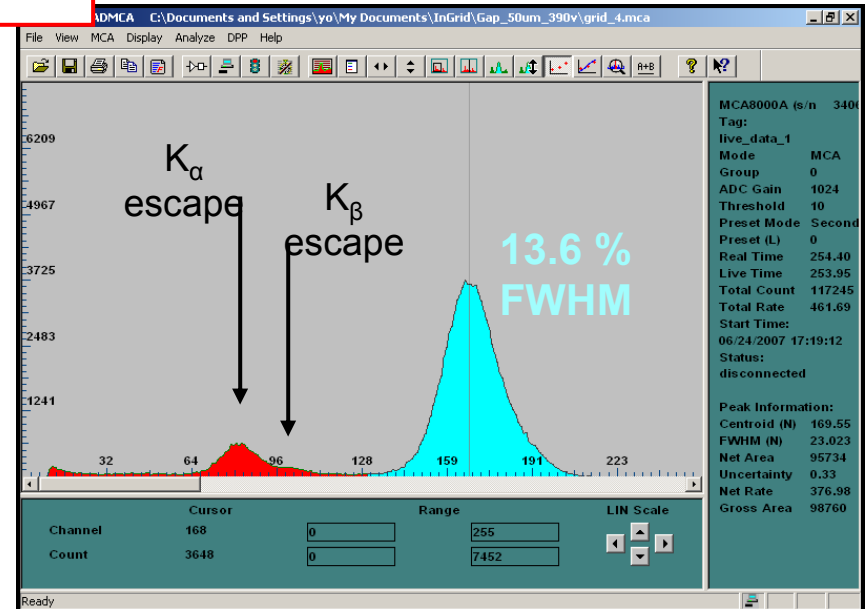
→ For now one TimePix & one Medipix are dead



# New InGrid developments and results

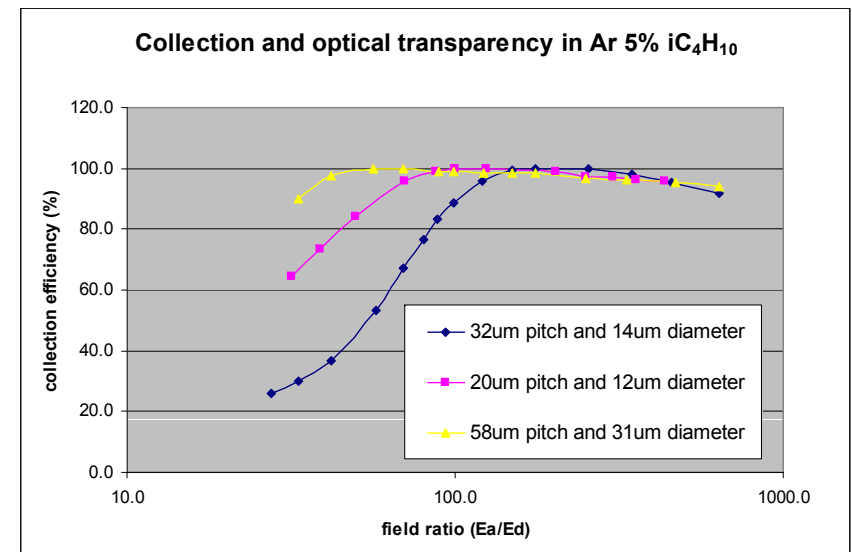
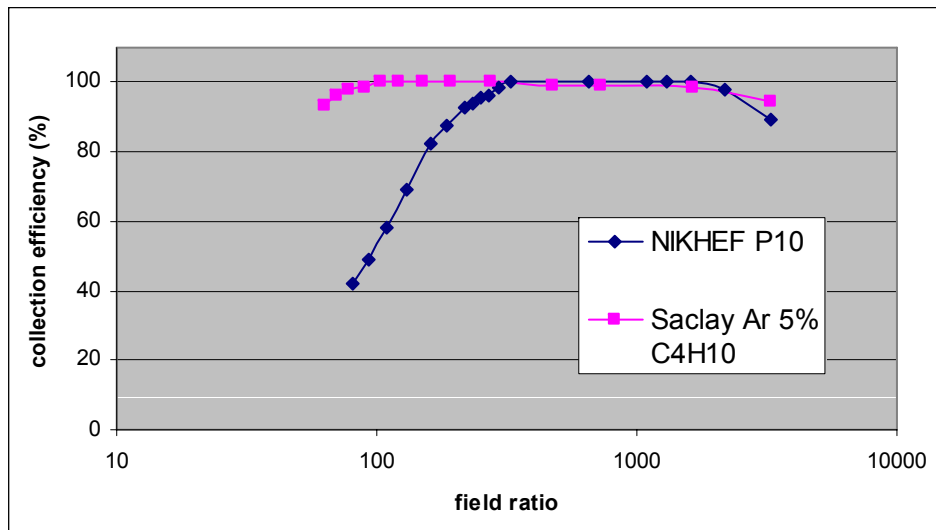
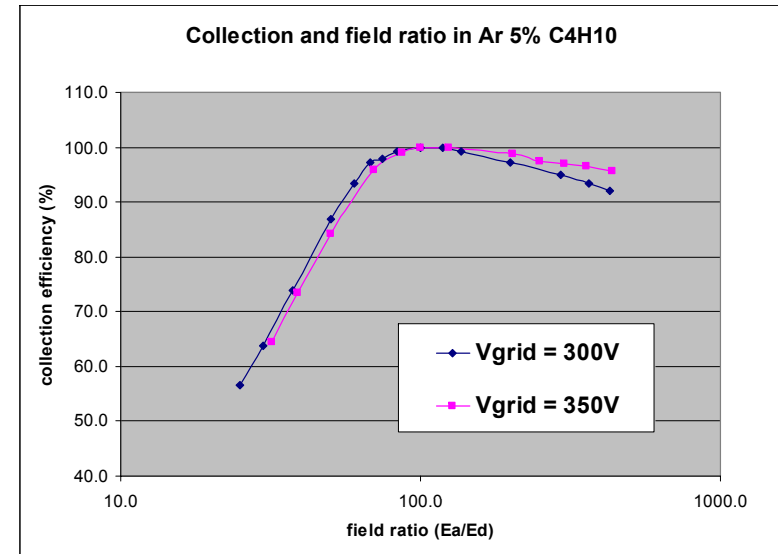
Max Chefdeville (NIKHEF/Saclay) + Twente Univ.

- Process improvement: grids much flatter
  - Extremely good energy resolution: 13.6 % FWHM with  $^{55}\text{Fe}$  in P10
  - Removal of  $K_{\beta}$  6.5 keV line:  
**11.7 % @ 5.9 keV in P10**
  - With  $F=0.17$  and  $\text{Ne} = 229$  gain fluctuation  $\sim 0.5$
- New wafer masks:  
hole pitches down to  $20\ \mu\text{m}$  with various diameters and gaps
  - Investigate Micromegas geometry
  - Test of the ion backflow theory feasible
- Until now:  $1\ \mu\text{m}$  thin Al but can now be increased to  $5\ \mu\text{m}$  by electrolysis  
Expect less damaged from sparks



# InGrid collection efficiency

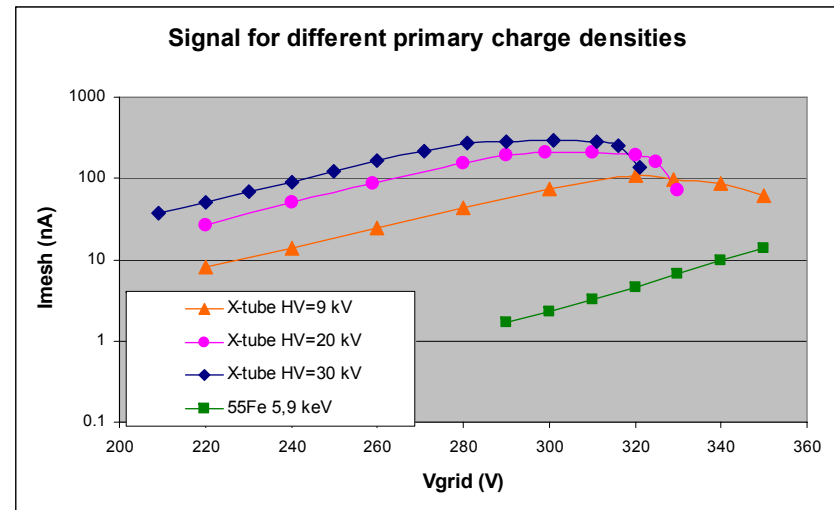
- Increase with field line compression ( $E_a/E_d$ ) and reach a plateau
- More compression for lower optical transparency grids
- Effect of the gas diffusion at the hole entrance: more compression for larger diffusion gas



# Ion backflow fraction

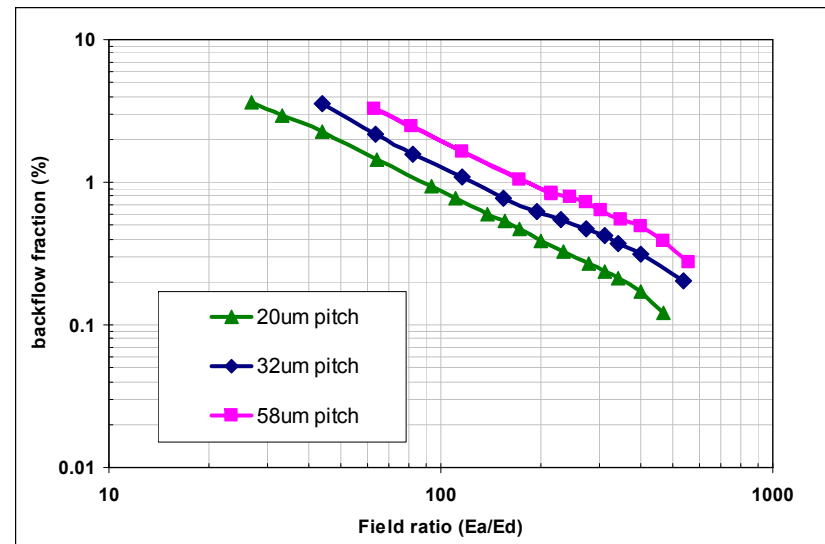
## Preliminary results in Ar 5% C<sub>4</sub>H<sub>10</sub>

- Annoying feature: small InGrid area
  - requires high primary Q density to get significant I<sub>0</sub>
  - Backflowing ions may recombine with primary e- !
  - Fine tuning of the collimation, the X-gun power (I<sub>0</sub> and Q density) and the gas gain

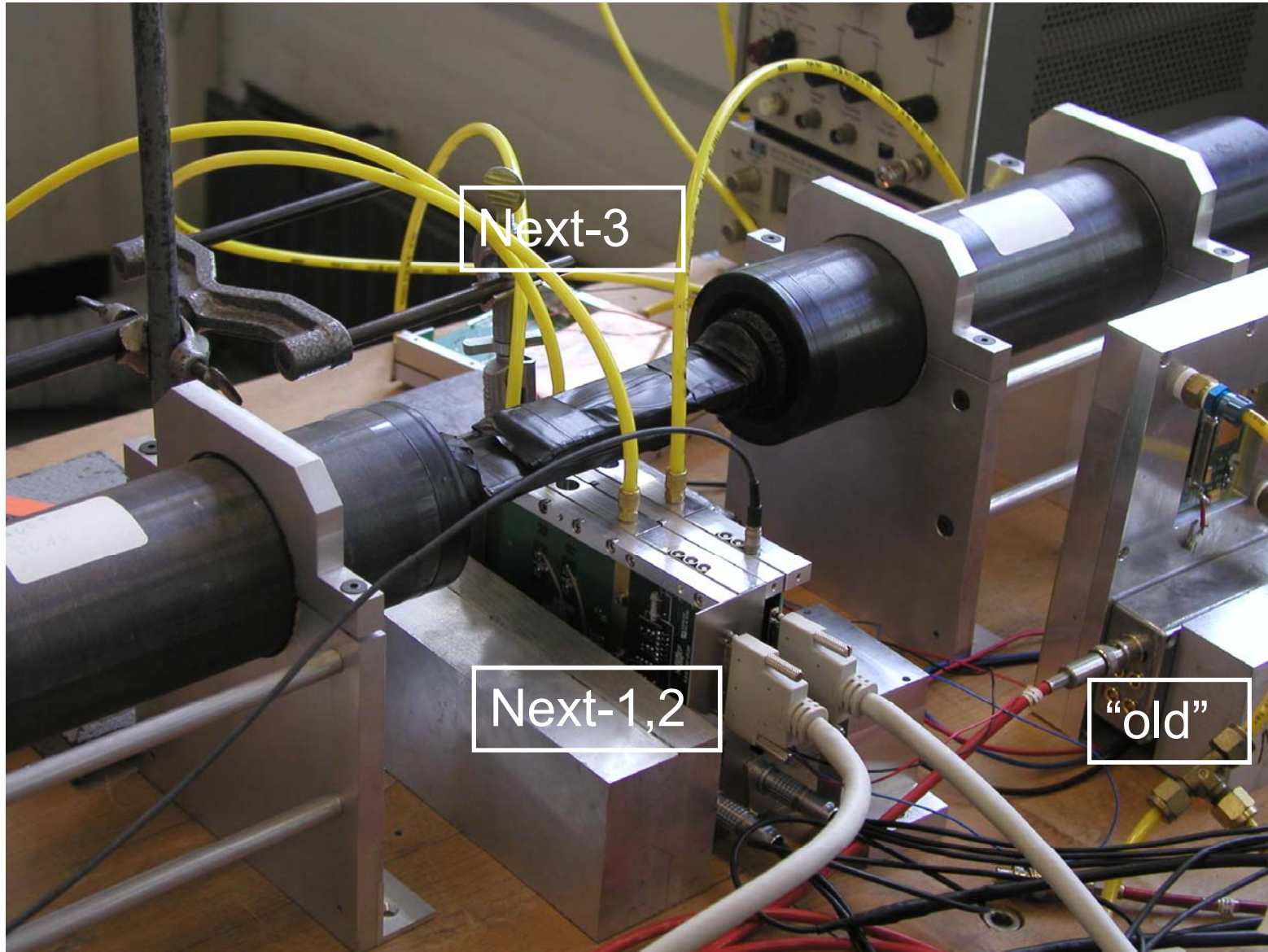


- **Results**
  - Curves follows 1/x trend
  - With  $\sigma \sim 14.2 \mu\text{m}$  over the 70  $\mu\text{m}$  gap

Pitch ( $\mu\text{m}$ )	$\sigma/p$	C (model)	C (measure)
20	0.71	1	0.9
32	0.44	1.2	1.3
58	0.25	2.5	2



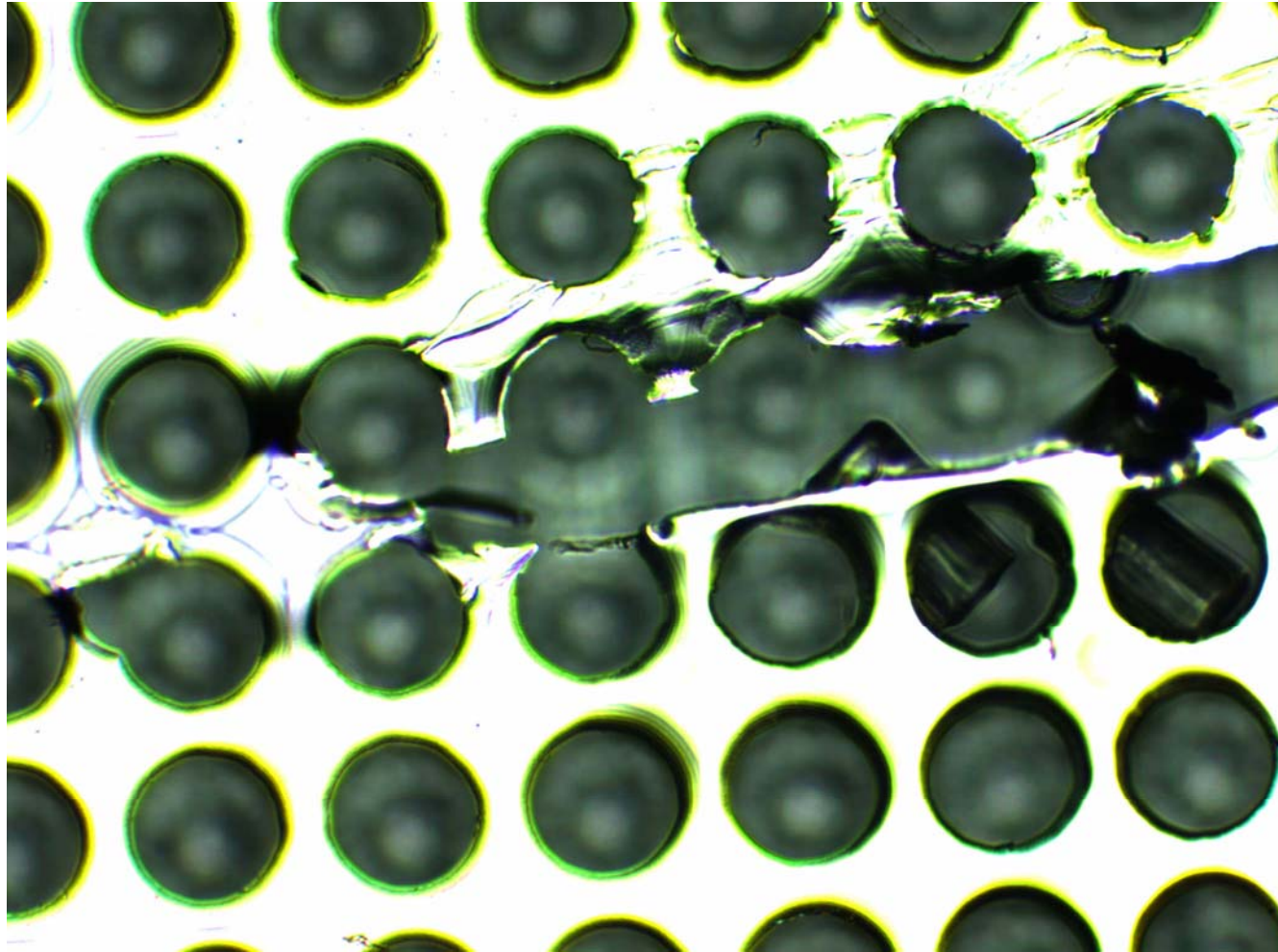
# NIKHEF setup (on 24 Aug. 2007)





# Status Timepix usage at NIKHEF

- 1<sup>st</sup> Timepix (with 3  $\mu\text{m}$  Siprot) “under HV” Dec-Jan for 40 days He/isoButane 80/20; then **died after ONE day with Ar/isoButane**
- Timepix C08-W0014 (also 3  $\mu\text{m}$  Siprot) was “under HV” since 24 April (for 3 months!) with He/isoButane 80/20
- Timepix E09-W0014 (with 20  $\mu\text{m}$  Siprot + Ingrid) under HV for one month with He/isoB (detector Next-1)
- Collecting cosmic m.i.p.’s in triggered mode (external shutter)
- Clock frequency 40 MHz and 100 MHz
- Pixelman: now writing “zero-suppressed” frames (< ~1 Kb) in “filtered” mode (only when >10 hits present)
- Detector Next-2: Timepix + 20  $\mu\text{m}$  Siprot + Micromegas; will go on Ar/isoB. next week
- Next-3: Medipix2.1 (**dead**) + 30  $\mu\text{m}$  Siprot + Ingrid: gain 200k

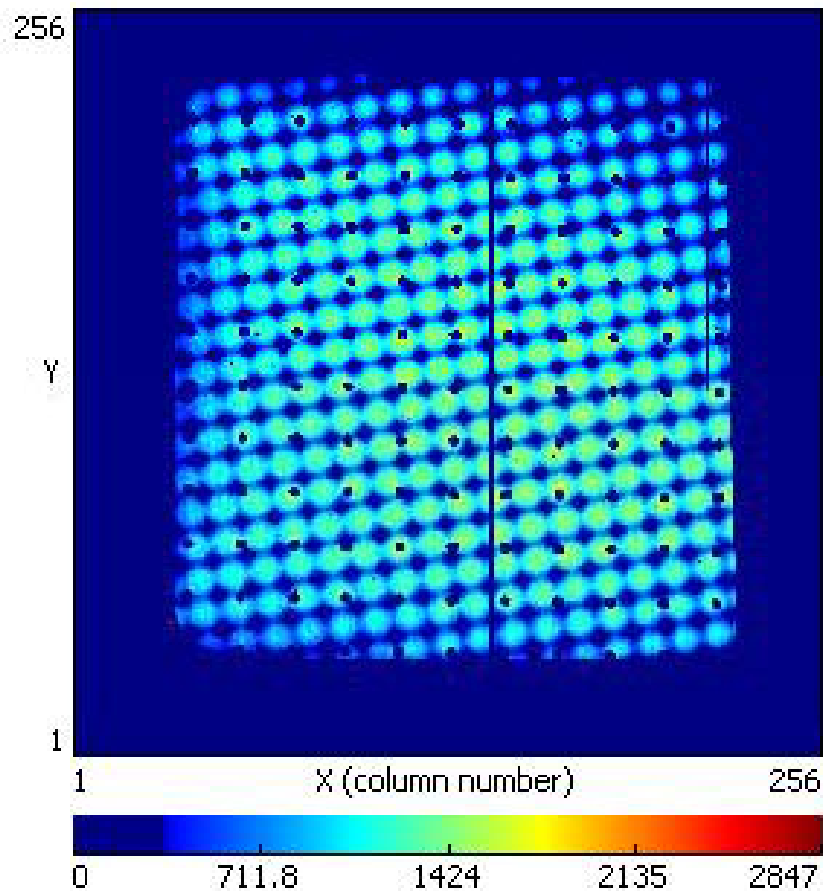


A “scratch” occurred during production Ingrid;  
Loose parts removed. Ingrid working!

Timepix + Micromegas

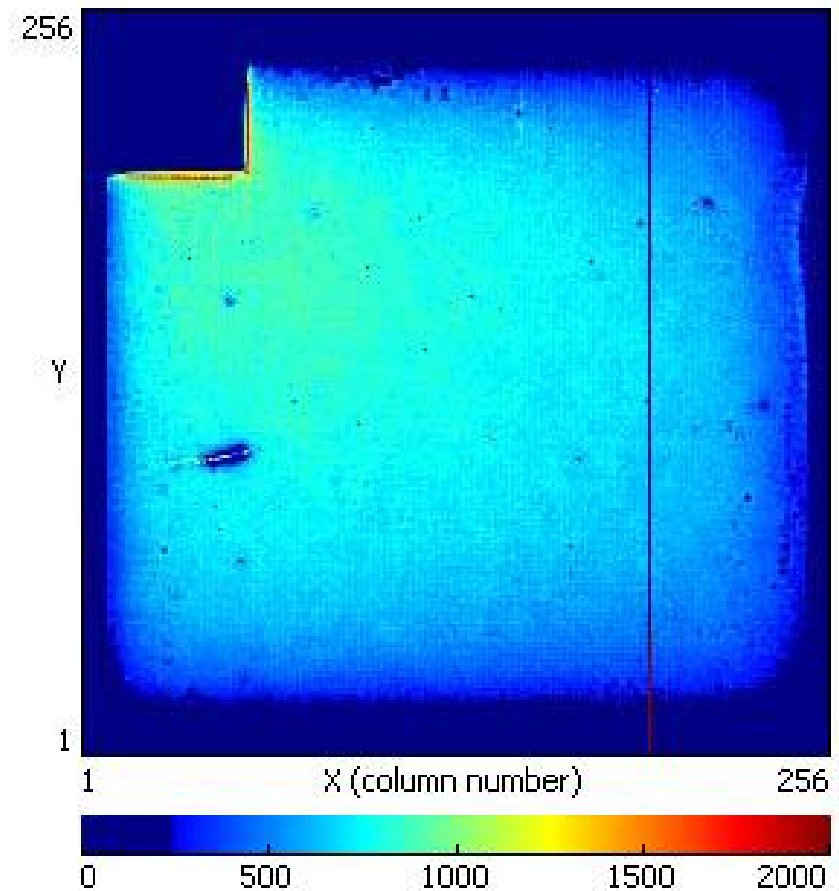
(in “counting” mode; 60 sec resp. 100 sec with  $^{90}\text{Sr}$  source)

Moire effects



Timepix + Ingrid

“uniform”



# Residuals and drift length

- Standard deviation of residuals follows  $\sigma_t^2 = \sigma_0^2 + D_t^2 \cdot z$  with  $\sigma_0$  spatial resolution at “0” drift distance and  $D_t$  diffusion coefficient.

- Straight line fit yields:

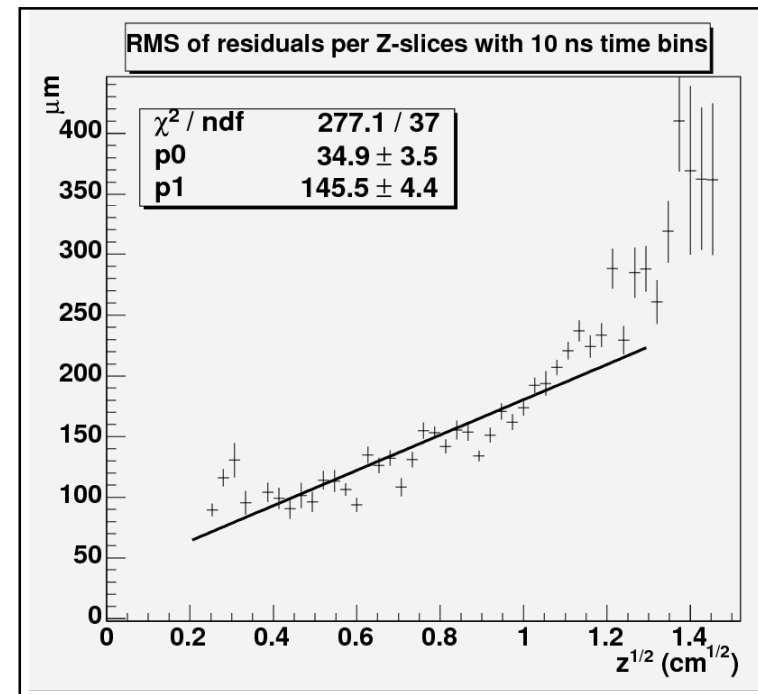
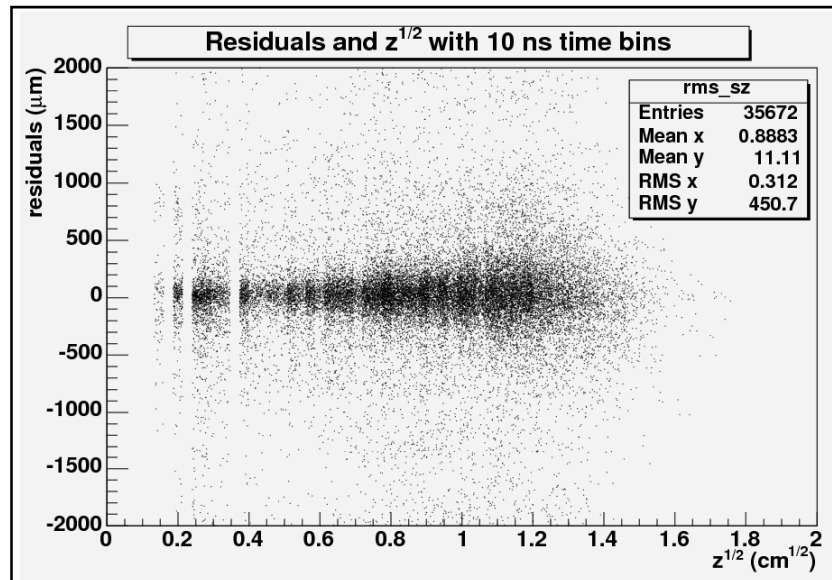
$$D_t = 174 \mu\text{m} \cdot \sqrt{\text{cm}} @ 660 \text{ V} \cdot \text{cm}^{-1}$$

$$D_t = 145 \mu\text{m} \cdot \sqrt{\text{cm}} @ 660 \text{ V} \cdot \text{cm}^{-1}$$

$$D_t = 180 \mu\text{m} \cdot \sqrt{\text{cm}} \text{ from MAGBOLTZ}$$

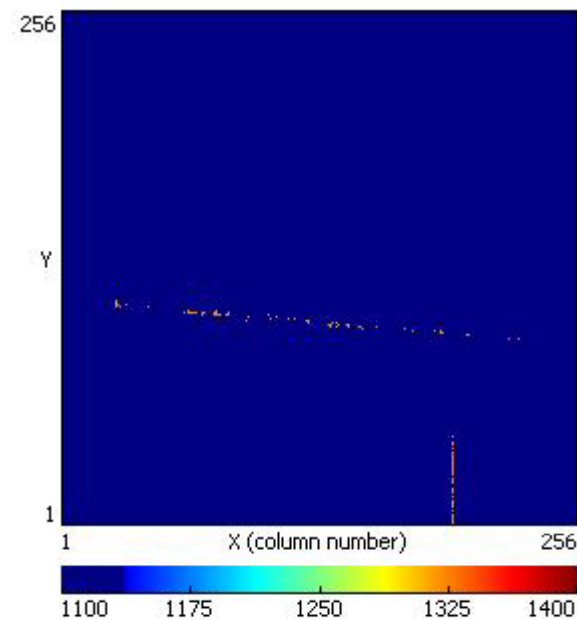
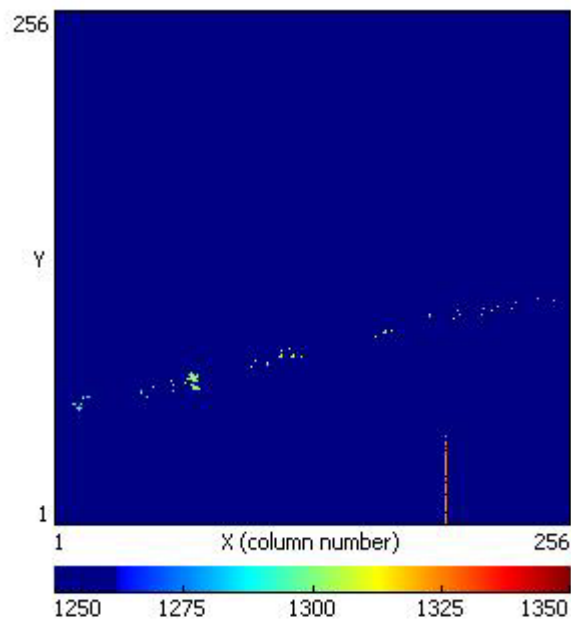
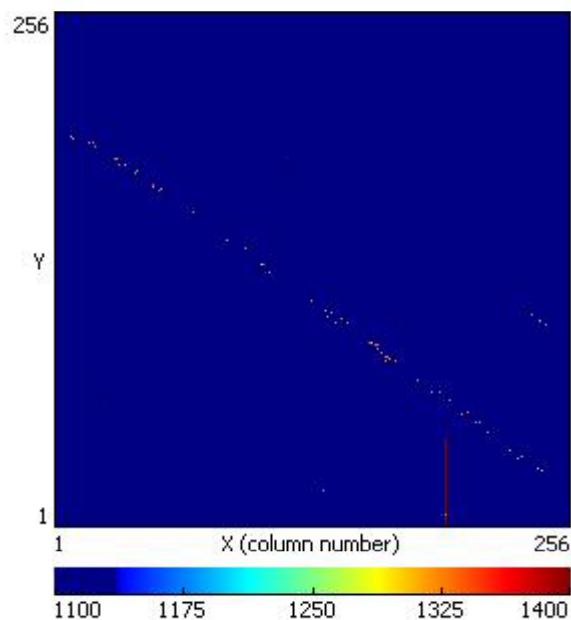
$$\text{for } t_{\text{bin}} = 25 \text{ ns}$$

$$\text{for } t_{\text{bin}} = 10 \text{ ns}$$



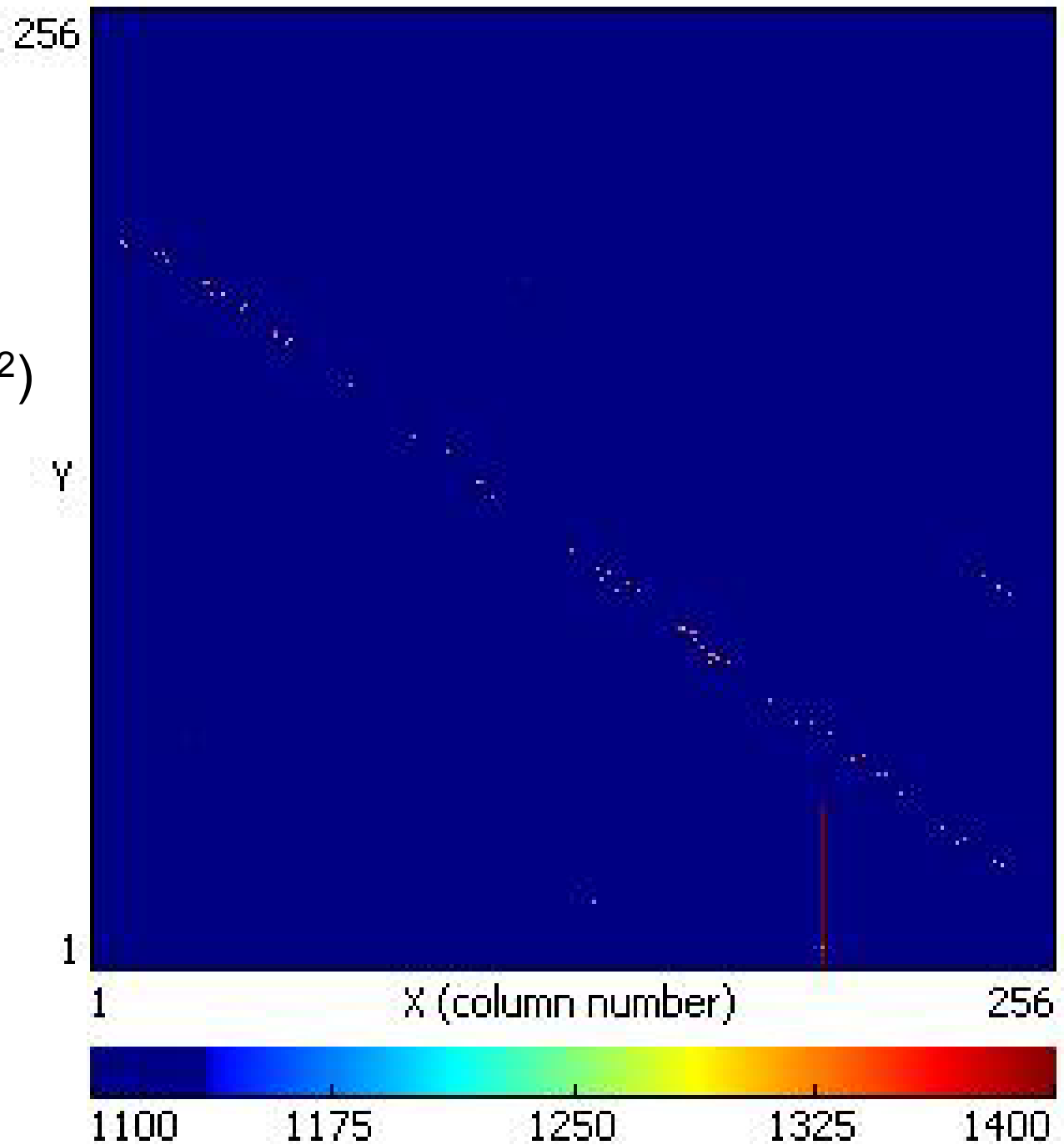
A few example cosmic tracks taken in triggered  
“arrival time” mode

(Timepix + 20  $\mu\text{m}$  thick Siprot + Ingrid)



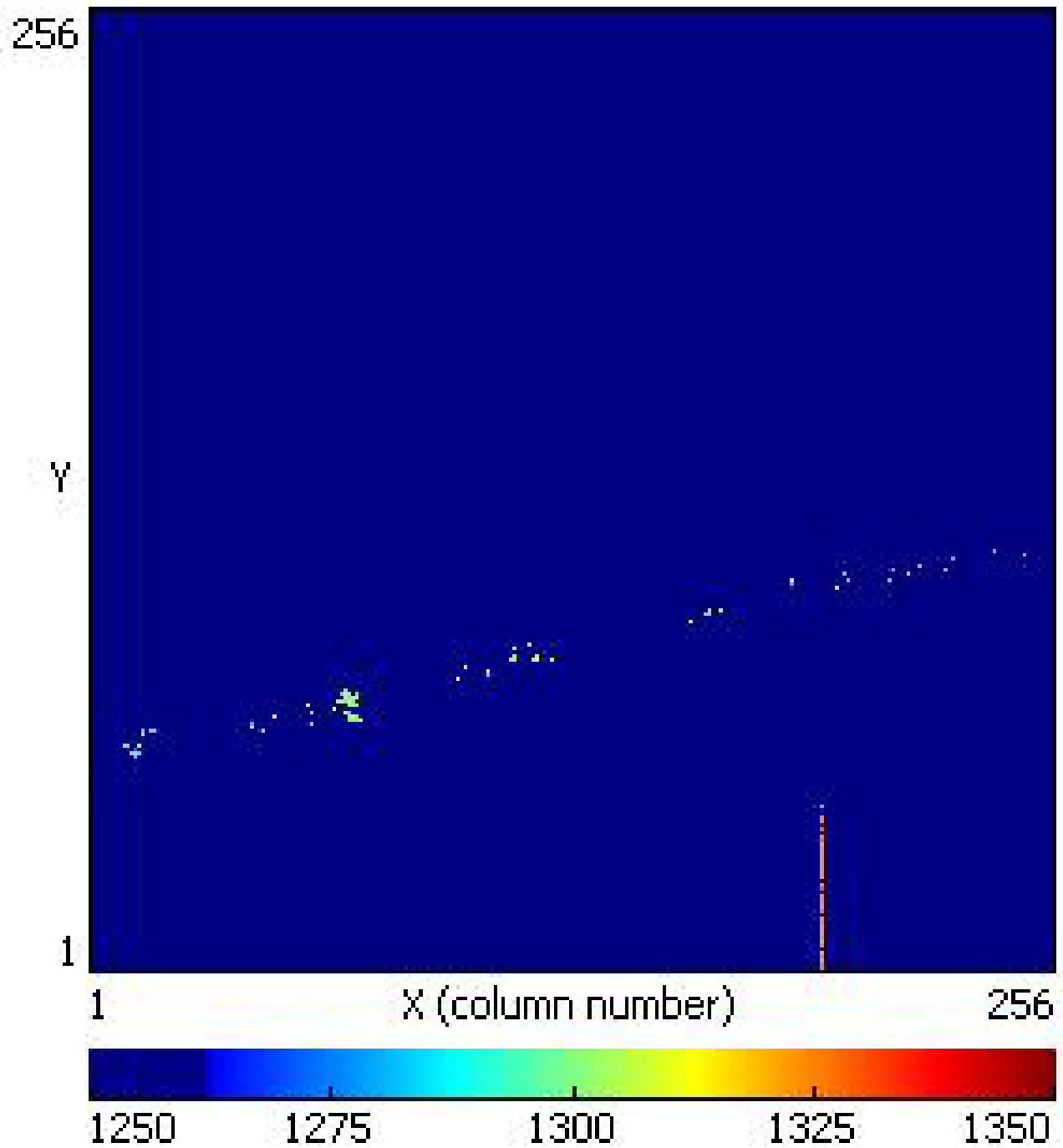
A “long” track  
(picture is 14x14 mm<sup>2</sup>)

Ingrid @ -420V



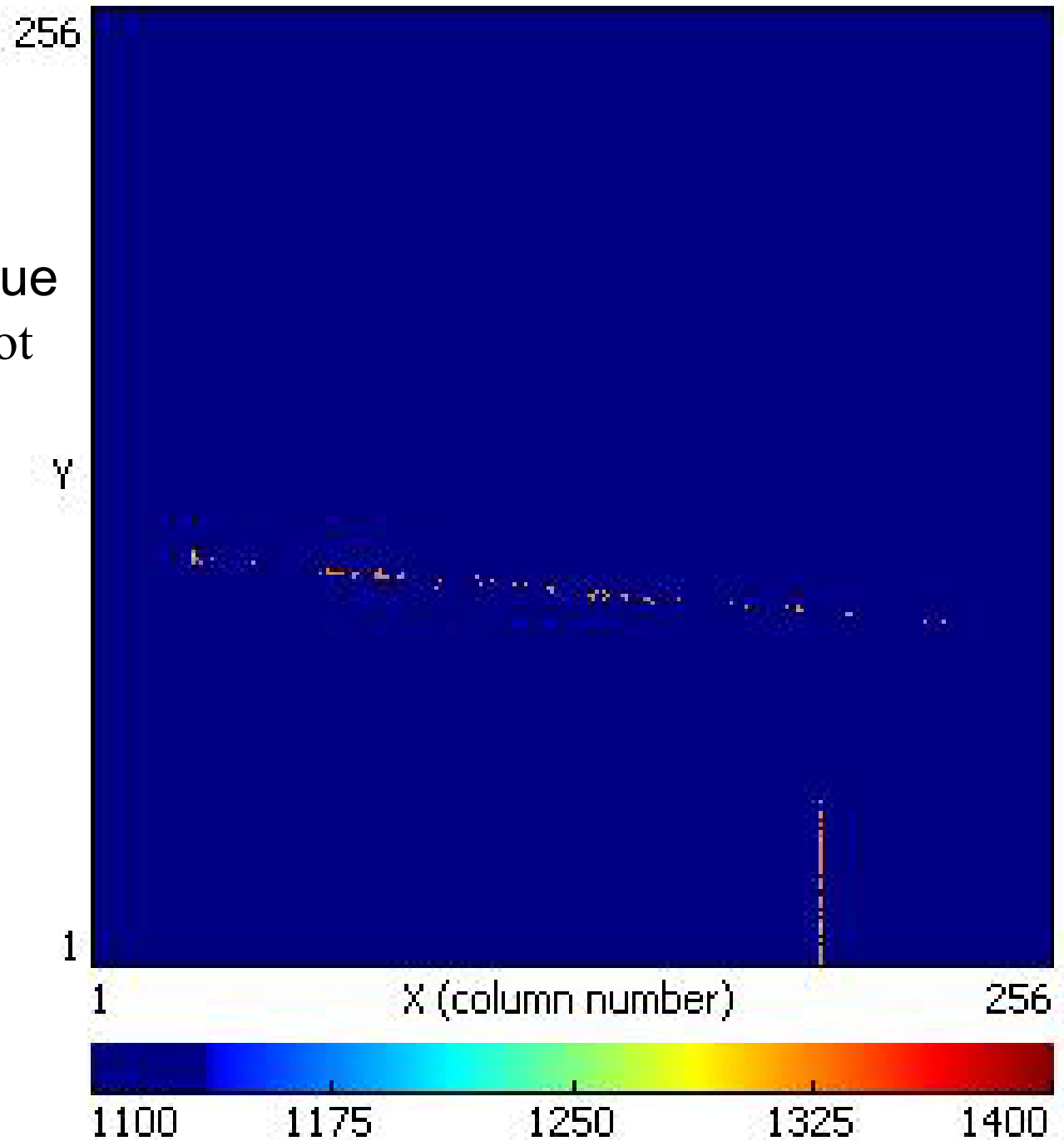
A “dipping” track

(Ingrid @ -450V)



“Multi-pixel” hits due to 20  $\mu\text{m}$  thick Siprot layer

Ingrid @ -450V

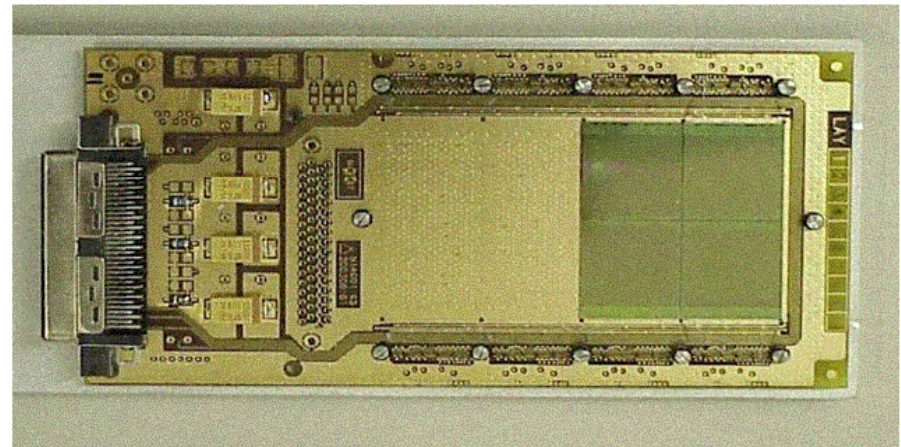




# Further Developments

RELAXD project (Dutch/Belgian)  
NIKHEF, Panalytical, IMEC, Canberra:

- **Chip tiling:** large(r) detector surfaces  
(2x2, 2x4 chips)
- **Through Si connectivity:** avoiding bonding wires
- **Fast readout technology**  
(~5 Gb/s)



Somewhat slower progress than expected:

Still hope for “through Si vias” (with Medipix chips) later this year!

# In summary: timetable

- ✓ 1<sup>st</sup> version Timepix operational: ~~1/2007~~ 9/2006
- ✓ First m.i.p. signals with Timepix: ~~~4/2007~~ 11/2006
- Gain experience with Timepix during 2007
- Development 2<sup>nd</sup> iteration Timepix during ~~2007~~  
→ 3/2008
- Endplate infrastructure: 1/2008
- Full SITPC infrastructure incl. DAQ available:  
1/2009

# Financial status

## Freiburg:

- from 17 month/person available for share of ALU about 4.5 will be spent this year
- consumables:  $\sim\frac{1}{2}$  still available
- all travel provisions spent

## Bonn:

- Postdoc 50% JRA2/SiTTPC, 50% NA2/ANALYS
- Cashflow as planned

## FOM/NIKHEF:

- Postdoc (Yevgen Bilevych) since 1 April '07
- Consumables  $\sim\frac{1}{2}$  spent

## CEA Saclay:

- Postdoc (David Attie)
- Consumables  $\sim\frac{1}{2}$  spent

## CERN:

- All SiTTPC money  $\sim$  spent